# **ON Semiconductor**



### FINAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

## 27 Nov 2007

### SUBJECT: ON Semiconductor Final Product/Process Change Notification #16071

TITLE: Final Notification of Qualification of Nantong-Fujitsu Microelectronics for Assembly/Test of TO-220AC Schottky & Ultrafast Rectifiers.

PROPOSED FIRST SHIP DATE: 27 Feb 2008

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly & Test Site

AFFECTED PRODUCT DIVISION(S): Automotive & Power Regulation Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION: Contact your local ON Semiconductor Sales Office or Mike Schager <a href="mailto:schager@onsemi.com">mike.schager@onsemi.com</a>>

SAMPLES: Contact your local ON Semiconductor Sales Office

#### ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Laura Rivers <a href="mailto:keylaura.rivers@onsemi.com">heylaura.rivers@onsemi.com</a>>

### **NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

### **DESCRIPTION AND PURPOSE:**

This is the FPCN to IPCN 16033 that announced the planned capacity expansion of ON Semiconductor's assembly and test operations of TO-220AC Discrete packaged products, currently built at the PSI Manila facility, to Nantong-Fujitsu's China facility. Upon the expiration of this FPCN, these Schottky & Ultrafast devices may be processed at either location. The Nantong-Fujitsu facility is currently used to manufacture ON's TO-220AB, I2PAK, & DPAK devices, and is ISO/TS 16949:2002 certified.

 There are minor changes to ON Semiconductor case outline 221B-04:

 F - Hole Diameter
 3.73 maximum to 4.09 maximum

 3.845
 3.837
 3.834
 3.836
 3.841
 3.837
 3.830
 3.827
 3.832
 3.830

 J - Lead Thickness
 0.46 minimum to 0.36 minimum
 0.393
 0.394
 0.395
 0.394
 0.392
 0.397
 0.396
 0.394

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### **RELIABILITY DATA SUMMARY:**

Schottky MBR60H100CTG. HTSL 150C, 1008 hrs 0/240 IOL Ta=25C, delta Tj=100C max, Ton=Toff=2 min, 8572 c 0/240 TC Ta=-65/+150C, 500 cycles 0/240 AC/PC 121C, 15psig, 100% RH, 96 hrs 0/240 Ultrafast MUR1660CTG TC Ta=-65/+150C, 500 cycles 0/240

## ELECTRICAL CHARACTERISTIC SUMMARY:

There are no changes in electrical characteristics; and product performance meets Data sheet specifications. Characterization data is available upon request.

# CHANGED PART IDENTIFICATION:

Product from Nantong-Fujitsu will be identified by NF site code marking.

## AFFECTED DEVICE LIST

BYW29-200G BYW80-200G MBR10100G MBR1035G MBR1045G MBR1060G MBR1080G MBR1090G MBR1635G MBR1645G MBR2515LG MBR40250G MBR735G MBR745G **MSR1560G MSR860G** MUR1510G MUR1515G MUR1520G MUR1540G MUR1560G MUR550PFG **MUR805G MUR8100EG MUR810G MUR815G** MUR820G MUR840G **MUR860G** MUR880EG